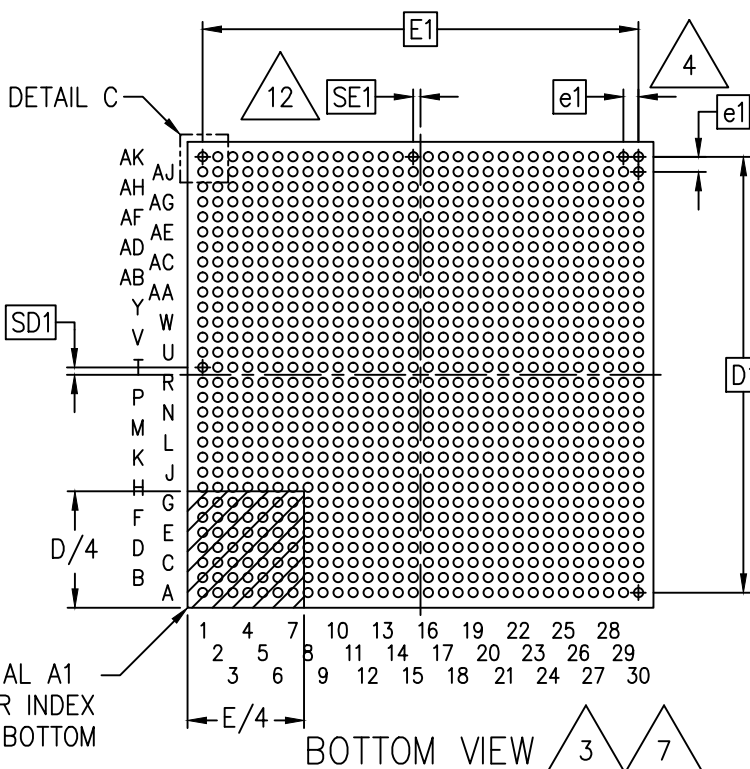
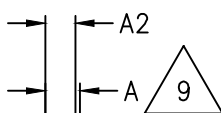
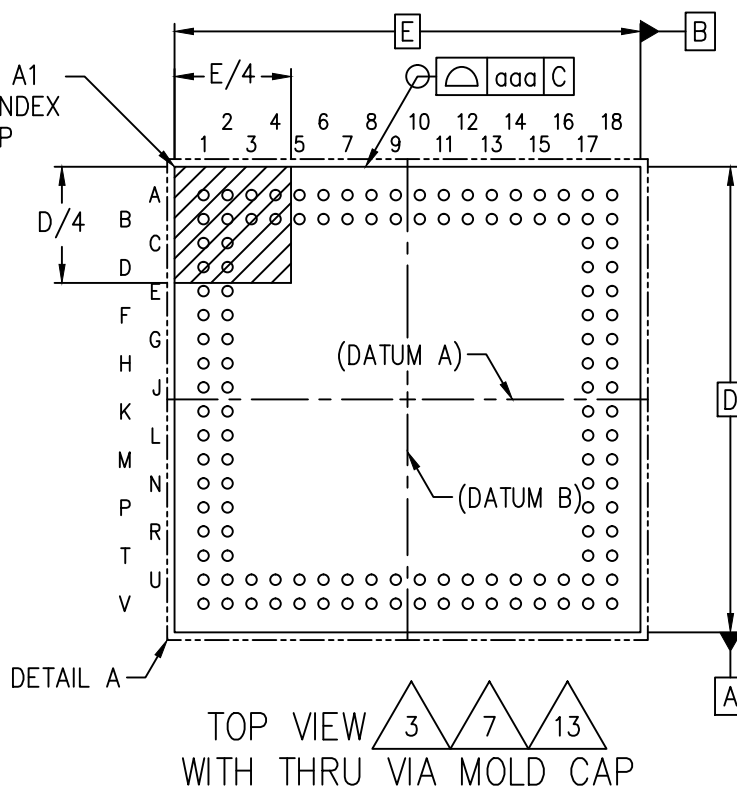


PATENT CLAIMS 16

IT IS REQUESTED THAT ANY FOOTPRINTS THAT ARE ADDED TO THIS MO ALSO BE ADDED TO THE CORRESPONDING UPPER POP PACKAGE.

11 TERMINAL A1 CORNER INDEX AREA, TOP



JEDEC SOLID STATE
PRODUCT OUTLINE
Copyright © 2016 JEDEC

THIS *REGISTERED OUTLINE* HAS BEEN PREPARED BY THE JEDEC JC-11 COMMITTEE AND REFLECTS A PRODUCT WITH ANTICIPATED USAGE IN THE ELECTRONICS INDUSTRY; CHANGES ARE LIKELY TO OCCUR.

LOWER POP BALL GRID
ARRAY FAMILY, SQUARE,
0.80 MM TOP, 0.50 MM BOT PITCH

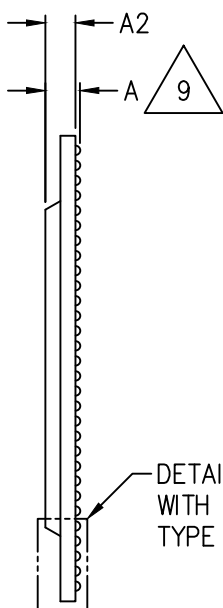
PACKAGE DESIGNATOR
S-XBGA

ITEM
MO-326

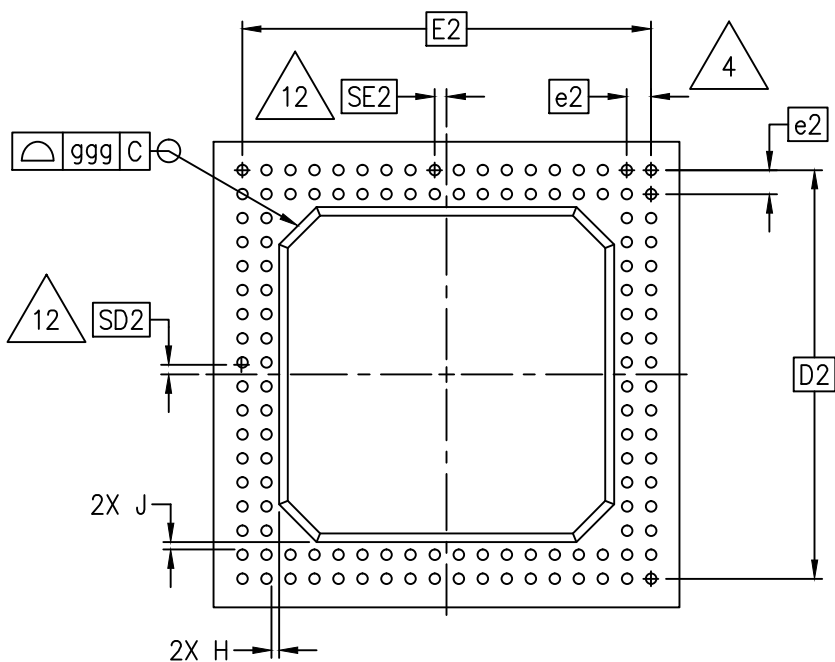
ISSUE
A

DATE
AUG 2016

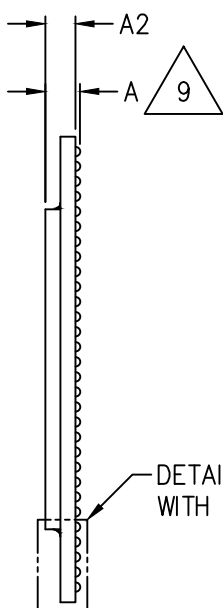
SHEET
1 OF 12



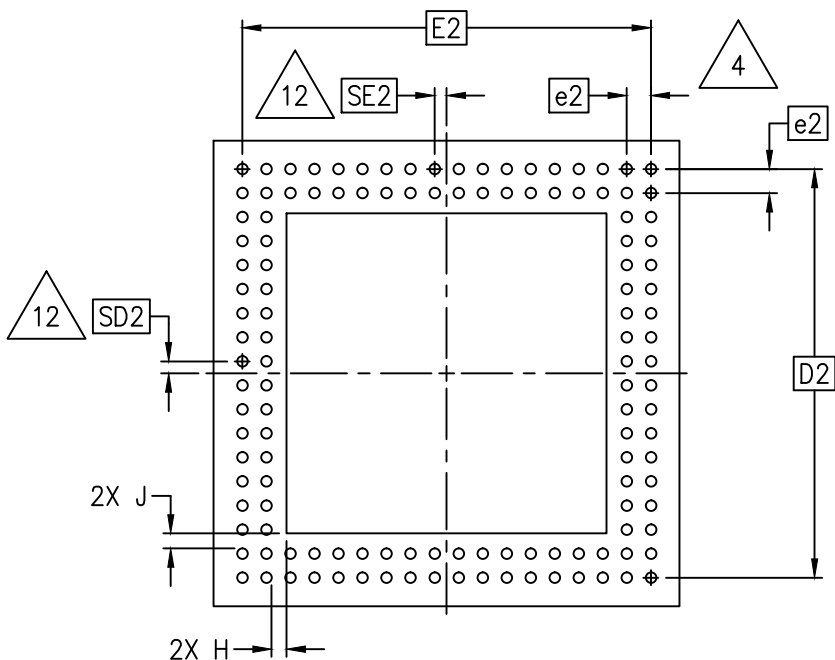
SIDE VIEW



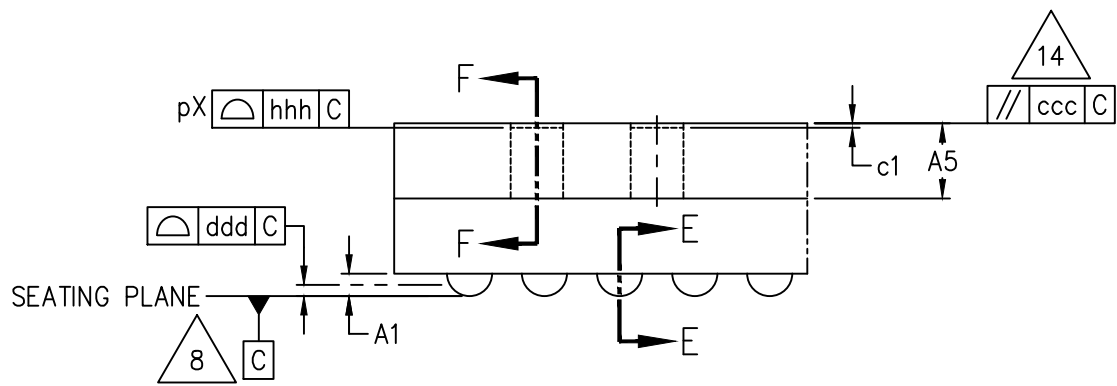
DETAIL A
WITH FLANGED TYPE MOLD CAP



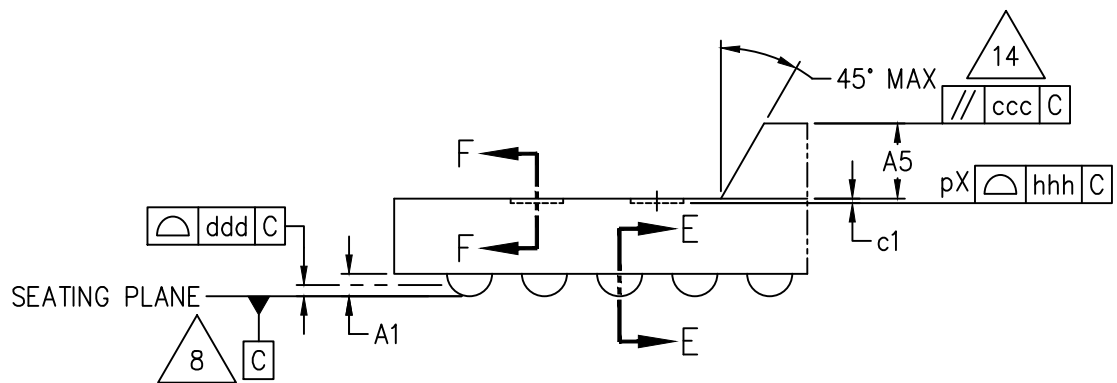
SIDE VIEW



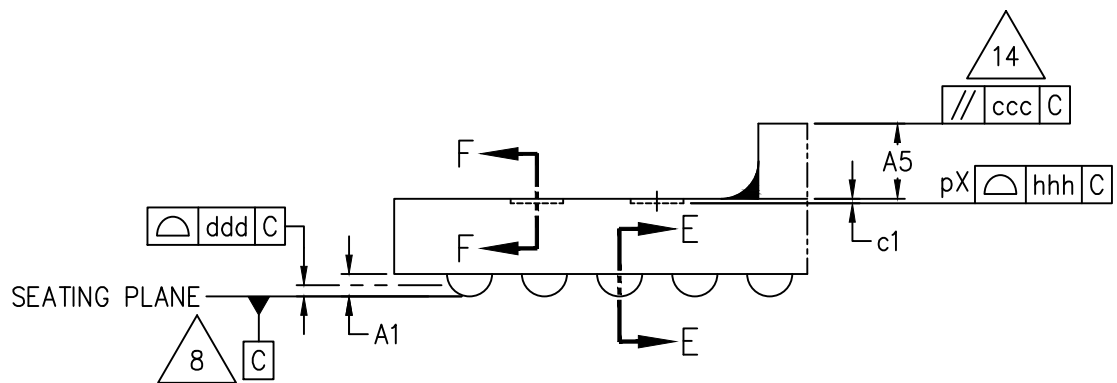
DETAIL A
WITH BARE DIE



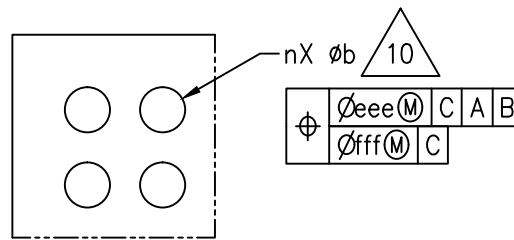
DETAIL B WITH THROUGH VIA MOLD CAP
(ROTATED 90° CW)



DETAIL B WITH FLANGED TYPE MOLD CAP
(ROTATED 90° CW)



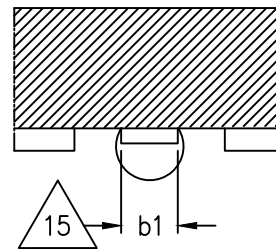
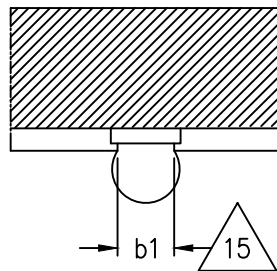
DETAIL B WITH BARE DIE
(ROTATED 90° CW)



DETAIL C
(PACKAGE BOTTOM)

TYPE 1 – SMD
(SOLDER MASK DEFINED)

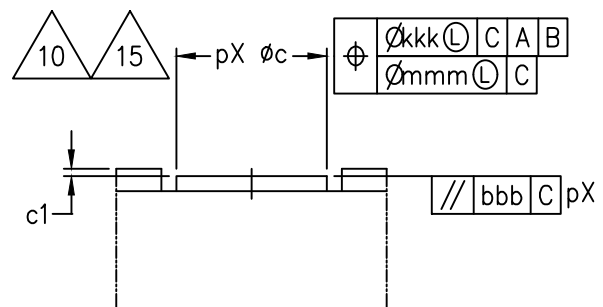
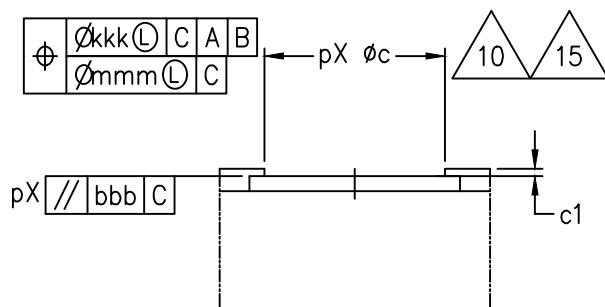
TYPE 2 – NSMD
(NON SOLDER MASK DEFINED)



SECTION E-E

TYPE 1 – SMD
(SOLDER MASK DEFINED)

TYPE 2 – NSMD
(NON SOLDER MASK DEFINED)



SECTION F-F